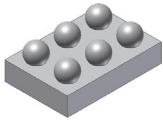


**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

ON Semiconductor®

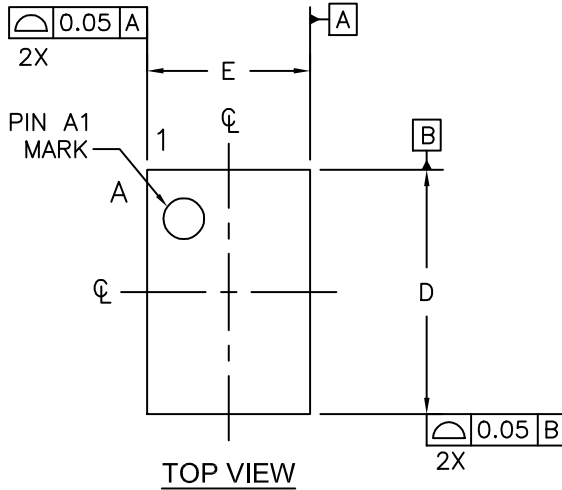


**WLCSP6 1.5x1x0.6**  
CASE 567PW  
ISSUE A

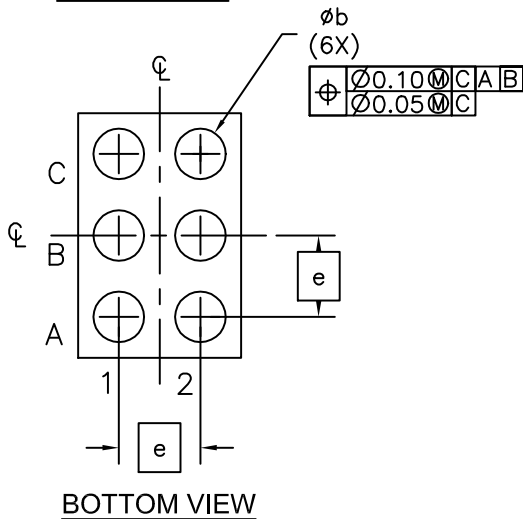
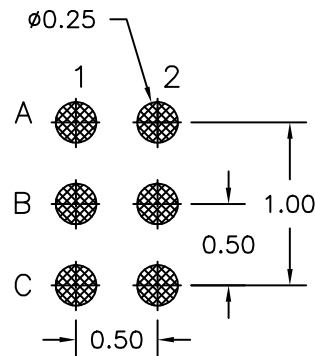
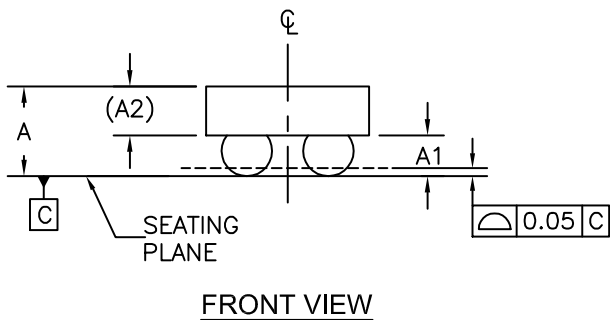
DATE 04 AUG 2021

NOTES: UNLESS OTHERWISE SPECIFIED

- A) ALL DIMENSIONS ARE IN MILLIMETERS.
- B) NO JEDEC REGISTRATION REFERENCE AS OF OCTOBER 2005.
- C) DRAWING CONFORMS TO ASME Y14.5M-2009



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	-	-	0.60
A1	0.22	0.25	0.28
A2	0.30 REF		
b	0.24	0.31	0.39
D	1.45	1.50	1.55
E	0.95	1.00	1.05
e	0.50 BSC		



**LAND PATTERN RECOMMENDATION**  
\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

<b>DOCUMENT NUMBER:</b>	<b>98AON13306G</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>WLCSP6 1.5x1x0.6</b>	<b>PAGE 1 OF 1</b>

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.